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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

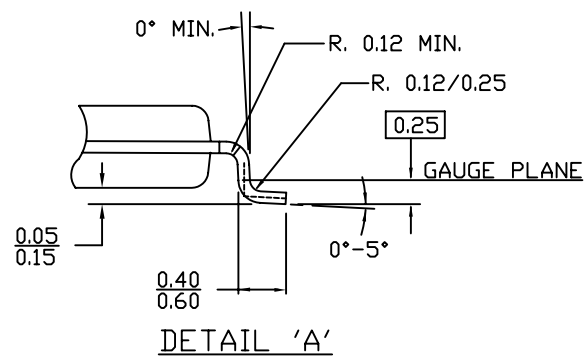
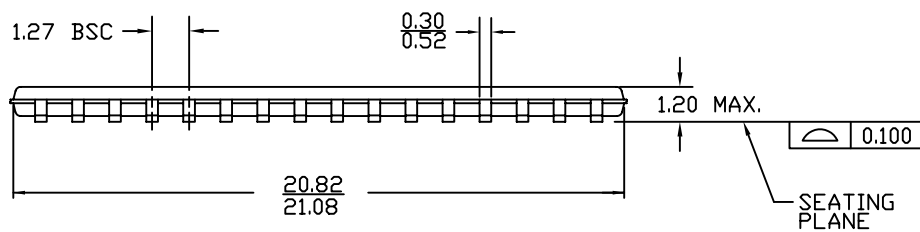
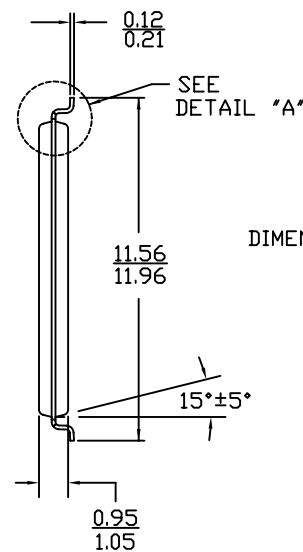
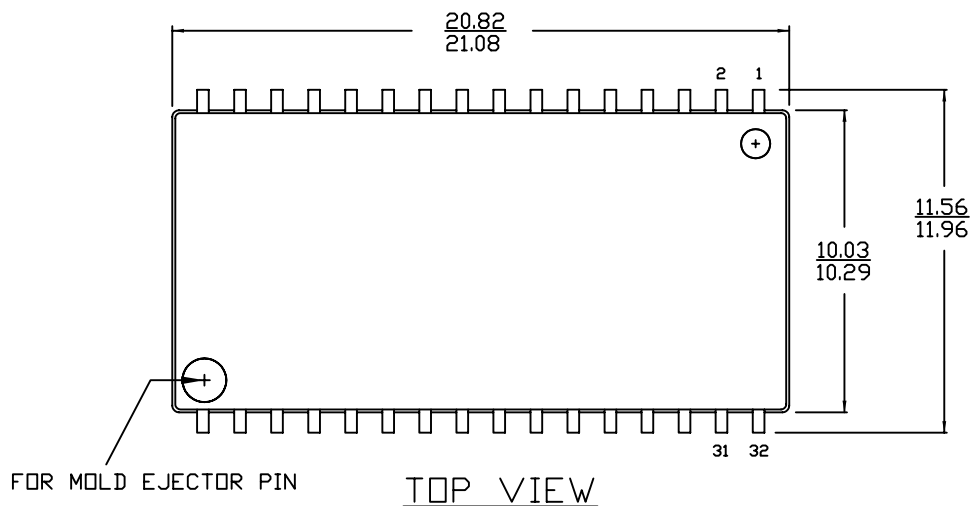
**Continuity of document content**


The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

**Continuity of ordering part numbers**

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

# 32 Lead TSOP TYPE II




		CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 32LD TSOP II 20.95X11.76X1.0 MM ZS32			
SPEC NO. 51-85095		REV *D	
SCALE		SHEET 1 OF 2	

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PACKAGE CODE(S)

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
ALL	-	**	52954	NEW RELEASE	10/30/97	N/A
ALL	-	*A	2866234	Changed Template and Title from 32LD TSOP TYPE II PKG. OUTLINE to PACKAGE OUTLINE, 32LD TSOP II 20.95X11.76X1.0 MM ZS32.	01/26/10	QAD
ALL	-	*B	3230060	NO CHANGE. SUNSET REVIEW.	04/16/11	TSV
ALL	-	*C	4585887	Sunset Review, Changed Drawing Template.	12/04/14	QAD
1	-	*D	4766599	Added FOR MOLD EJECTOR PIN on TOP VIEW.	05/15/15	QAD

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